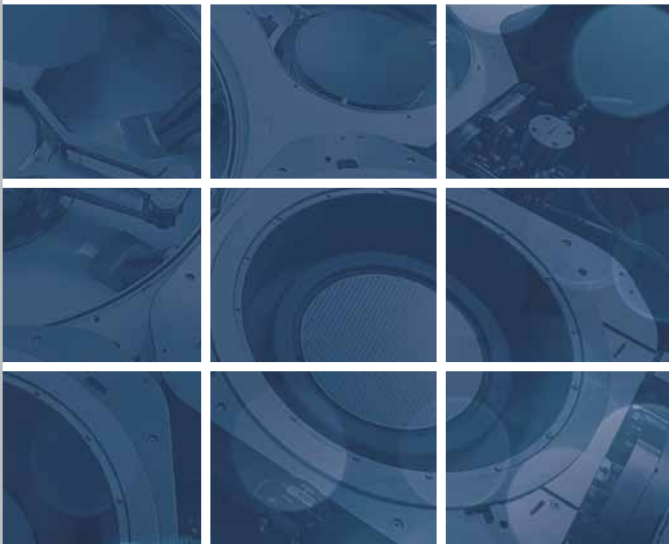


Global Semiconductor Packaging Materials Outlook



Global Semiconductor Packaging Materials Outlook is a comprehensive market research study that examines semiconductor packaging technology trends and their impact on the packaging materials markets. Packaging materials markets are quantified; new opportunities are highlighted for advanced technology nodes and emerging package form factors; and market forecasts through 2017 are presented.

Global Semiconductor Packaging Materials Outlook is an essential business tool for anyone interested in the plastic packaging materials arena. Packaging materials directly affect the performance, reliability and cost of semiconductors, and offer significant improvement potential.

Material segments covered include:

- Organic Substrates
- Leadframes
- Mold Compounds
- Bonding Wire
- Underfill Materials
- Die Attach Adhesives
- Liquid Encapsulants
- Thermal Interface Materials
- Solder Balls
- Wafer Level Package (WLP) Dielectrics

Features

- Technology trends
- Regional market size
- Five-year market forecasts
- Supplier market share
- Market size in revenue and units
- Capacity and utilization trends
- Average selling prices and trends

This study has a user-friendly electronic format and includes:

- Concise executive summary
- Adobe Acrobat chapters for each materials segment
- Excel workbook file summarizing market information
- PowerPoint charts, ideal for presentations

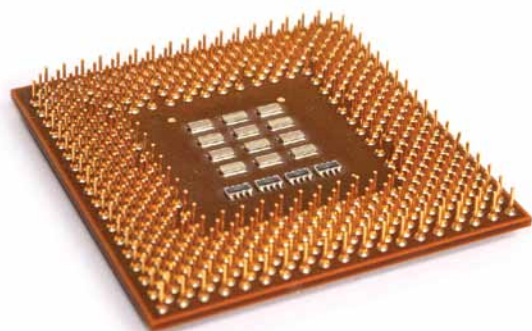
Methodology

In-person interviews with material suppliers, packaging subcontractors and semiconductor manufacturers around the world are the sources of information for this study. Market size information is developed through primary research and modeling. Five-year market forecasts are developed based on different scenarios of new technology penetration and market growth.

CONDENSED TABLE OF CONTENTS

1. Introduction Methodology Assumptions Report Organization	4. Leadframes Technology Trends Markets Price Trends Market Forecasts Supply and Market Share	7. Underfill Materials Technology Trends Market and Forecasts Supply and Market Share	10. Solder Balls Technology Trends Market and Forecasts Supply and Market Share
2. Semiconductor Packaging Technology Challenges Packaging Outsourcing End-market Applications	5. Bonding Wire Technology Trends Markets Price Trends Market Forecasts Supply and Market Share	8. Liquid Encapsulants Technology Trends Markets Price Trends Market Forecast Supply and Market Share	11. Wafer Level Package Dielectrics Technology Trends and Forecast Suppliers
3. Substrates Laminate Substrates • Technology Trends • Market and Forecasts • Price Trends • Supply and Market Share Flex Circuit/Tape Substrates • Technology Trends • Market and Forecasts • Price Trends • Suppliers	6. Mold Compounds Technology Trends Markets Price Trends Market Forecasts Supply and Market Share	9. Die Attach Materials Technology Trends Markets Price Trends Market Forecasts Supply and Market Share	12. Thermal Interface Materials Technology Trends Material Types Market Forecast Material Supply
			13. Summary and Conclusions
			14. Appendices

Pricing Information—Global Semiconductor Packaging Materials Outlook



	SEMI Members*	Non-Members
Single-user	\$5,000	\$6,000
Multi-user License	\$10,000	\$12,500

• This pricing does not apply to Individual Members.

How to Order

Visit SEMI at www.semi.org/store

For more information, call SEMI Global Customer Service at 1.877.746.7788 (U.S. toll-free) or 1.408.943.6901.

www.semi.org/store



About SEMI

SEMI is the global industry association serving the nano and microelectronics manufacturing. SEMI member companies are the engine of the future, enabling smarter, faster and more economical products that improve our lives. SEMI maintains offices in Beijing, Bengaluru, Berlin, Brussels, Grenoble, Hsinchu, Moscow, San Jose, Seoul, Shanghai, Singapore, Tokyo, and Washington, D.C.

For more information visit www.semi.org

For more information, please contact Dan P.Tracy, Ph.D, senior director of Industry Research and Statistics, SEMI at dtracy@semi.org or at 1.408.943.7987.

About TechSearch International, Inc.

Founded in 1987, TechSearch International (Austin, Texas) is a technology licensing and consulting company specializing in accurate, relevant, and timely information on advanced packaging technology and market developments. For more information, visit TechSearch International, Inc. at www.techsearchinc.com.

For more information, please contact Ms. E. Jan Vardaman, president and founder, TechSearch International, Inc. at jan@techsearchinc.com or at 1.512.372.8887.

